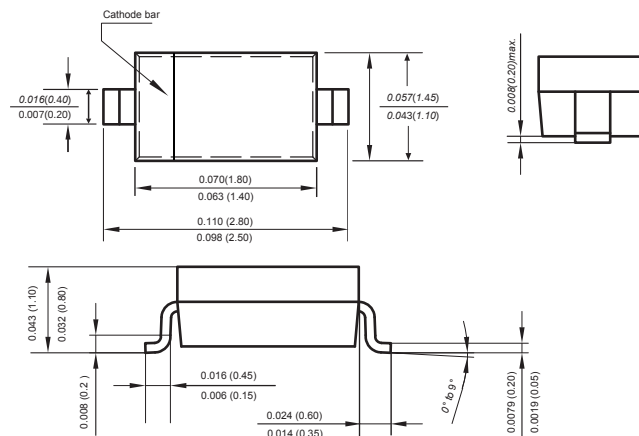


SURFACE MOUNT GLASS PASSIVATED FAST RECOVERY RECTIFIER

Features

- ◆ Glass passivated Chip Junction
- ◆ Low forward voltage drop
- ◆ Low leakage current
- ◆ For surface mounted applications
- ◆ Low profile package
- ◆ Easy to pick and place
- ◆ Lead free in comply with EU RoHS 2011/65/EU directives

SOD-323



Dimensions in inches and (millimeters)

Mechanical Data

Case : SOD-323

Terminals : Solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Appro. Weight : 0.00019 ounce, 0.0548 grams

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	FR101WS	FR102WS	FR103WS	FR104WS	FR105WS	FR106WS	FR107WS	UNITS
Marking Code		1R	2R	3R	4R	5R	6R	7R	
Maximum repetitive peak reverse voltage	V _{RMM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current	I _{F(AV)}	1.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed onrated load (JEDEC Method)	I _{FSM}	15							A
Maximum instantaneous forward voltage at 1.0A	V _F	1.3							V
Maximum DC reverse current T _A =25℃ at rated DCblocking voltage T _A =125℃	I _R	5 50							uA
Typical junction capacitance (NOTE 3)	C _J	5							pF
Typical reverse recovery time (NOTE 2)	T _{rr}	150				250	500		ns
Operating junction temperature range	T _J	-55 to +125							℃
Storage temperature range	T _{STG}	-55 to +150							℃

Note: 1.P.C.B. mounted with 0.2" X 0.2" (5 X 5 mm) copper pad areas.

2.Measured with $I_F=0.5A$, $I_R=1A$, $t_{rr}=0.25A$

3.Measured at 1.0MHz and applied reverse voltage of 4.0V D.C.

4.The typical data above is for reference only.

Typical Characteristics

Fig.1 Forward Current Derating Curve

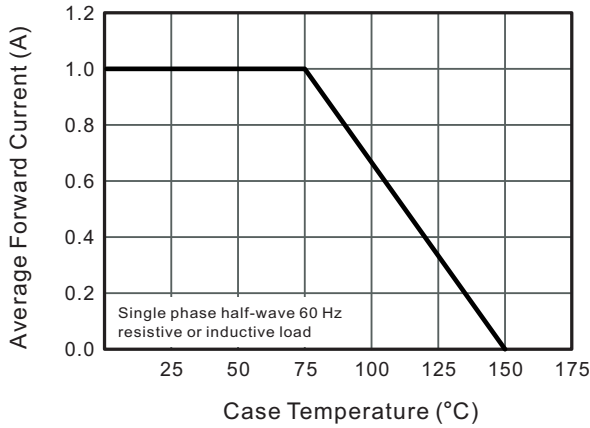


Fig.2 Typical Instantaneous Reverse Characteristics

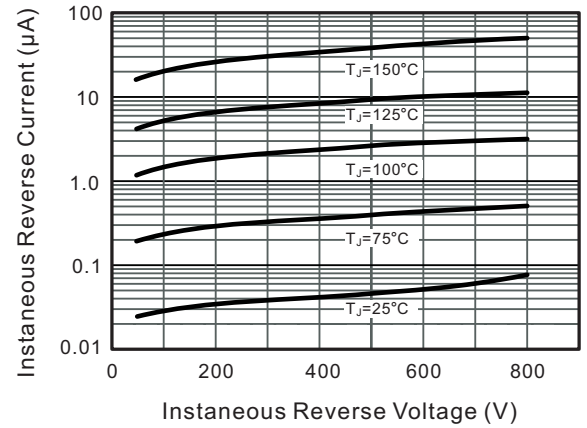


Fig.3 Typical Forward Characteristic

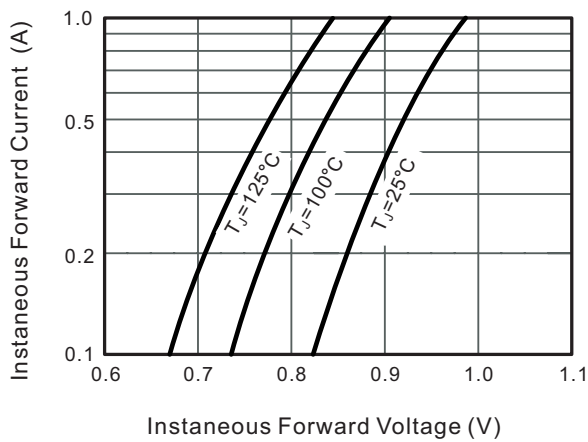


Fig.4 Typical Junction Capacitance

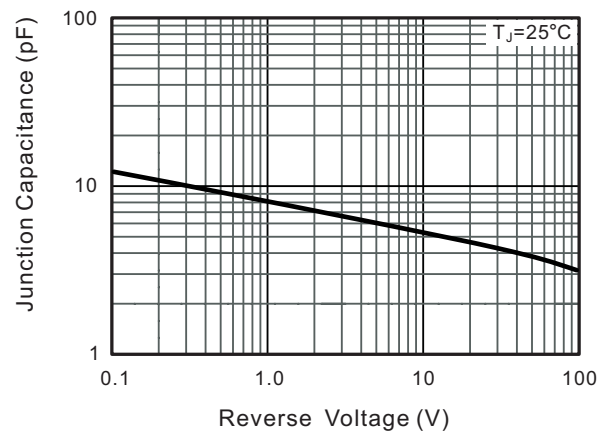
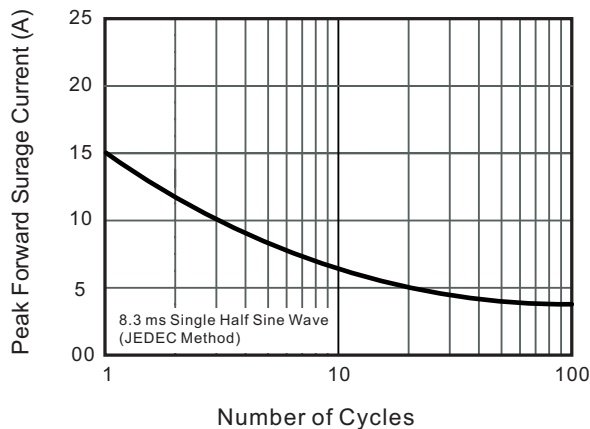
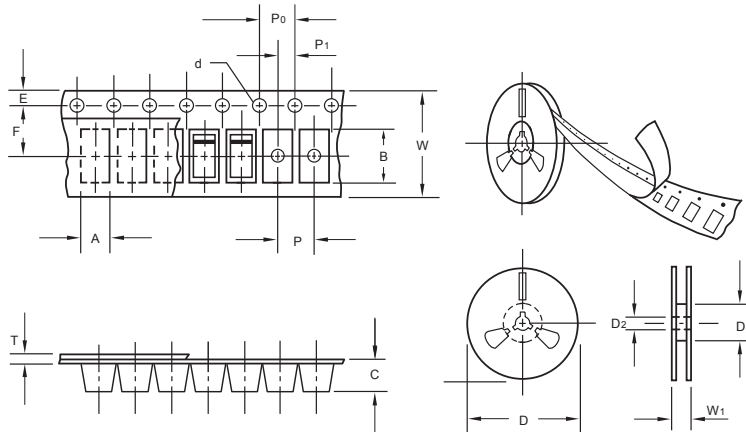


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



The curve above is for reference only.

Packing information



unit:mm

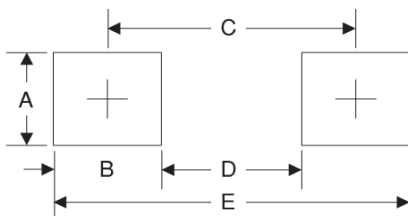
Item	Symbol	Tolerance	SOD-323
Carrier width	A	0.1	1.46
Carrier length	B	0.1	2.90
Carrier depth	C	0.1	1.25
Sprocket hole	d	0.05	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D ₁	min	50.00
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D ₁	min	54.40
Feed hole diameter	D ₂	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P ₀	0.1	4.00
Embossment center	P ₁	0.1	2.00
Overall tape thickness	T	0.1	0.06
Tape width	W	0.3	8.00
Reel width	W ₁	1.0	12.30

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA. (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SOD-323	7"	3,000	4.0	45,000	210*208*203	178	430*430*235	180,000	9.0

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.2	0.047
B	1.2	0.047
C	2.6	0.141
D	1.4	0.055
E	3.8	0.149